

650V Super-junction Power MOSFET

Description

650V Super-junction Power MOSFET

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The Multi-EPI SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

Features

- Very low FOM RDS(on)×Qg
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

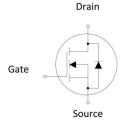
Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger

TO-220F









Device Marking and Package Information

Device	Package	Marking
TPA65R950M	TO-220F	65R950M
TPD65R950M	TO-252	65R950M

Key Performance Parameters

Parameter	Value	Unit
V _{DS} @ T _{j,max}	700	V
R _{DS(on),max}	0.95	Ω
$Q_{g,typ}$	9.6	nC
I _D	4.5	A
I _{D,pulse}	13.5	A
E _{OSS} @ 400V	1.04	μJ
Body Diode di _F /dt	500	A/μs



Absolute Maximum Ratings T _C = 25°C, unless otherwise noted					
Parameter			Symbol	Value	Unit
Oction of Both Oction	T _C = 25°C			4.5	A
Continuous Drain Current	T _C = 100°C		I _D	2.7	
Pulsed Drain Current		(note1)	I _{D,pulse}	13.5	Α
Gate-Source Voltage			V_{GSS}	±30	V
Single Pulse Avalanche Energy		(note2)	E _{AS}	50	mJ
Repetitive Avalanche Energy (note2)		E _{AR}	0.15	mJ	
Avalanche Current		I _{AR}	1.0	Α	
MOSFET dv/dt Ruggedness, V _{DS} = 0480V		dv/dt	50	V/ns	
Power Dissipation For TO-220F			26	10/	
Power Dissipation For TO-252			P_{D}	37	W
Continuous Diode Forward Current			I _S	3.8	_
Diode Pulsed Current (note1)		(note1)	I _{S,pulse}	13.5	A
Reverse Diode dv/dt (note3)		dv/dt	15	V/ns	
Maximum Diode Commutation	Speed	(note3)	di _f /dt	500	A/µs
Operating Junction and Storage	Temperature Range		T_J,T_stg	-55~+150	°C

Thermal Resistance For TO-220F			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	4.9	°C/W
Thermal Resistance, Junction-to-Ambient	R _{thJA}	80	-0/00

Thermal Resistance For TO-252			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	3.4	90/1/
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	°C/W

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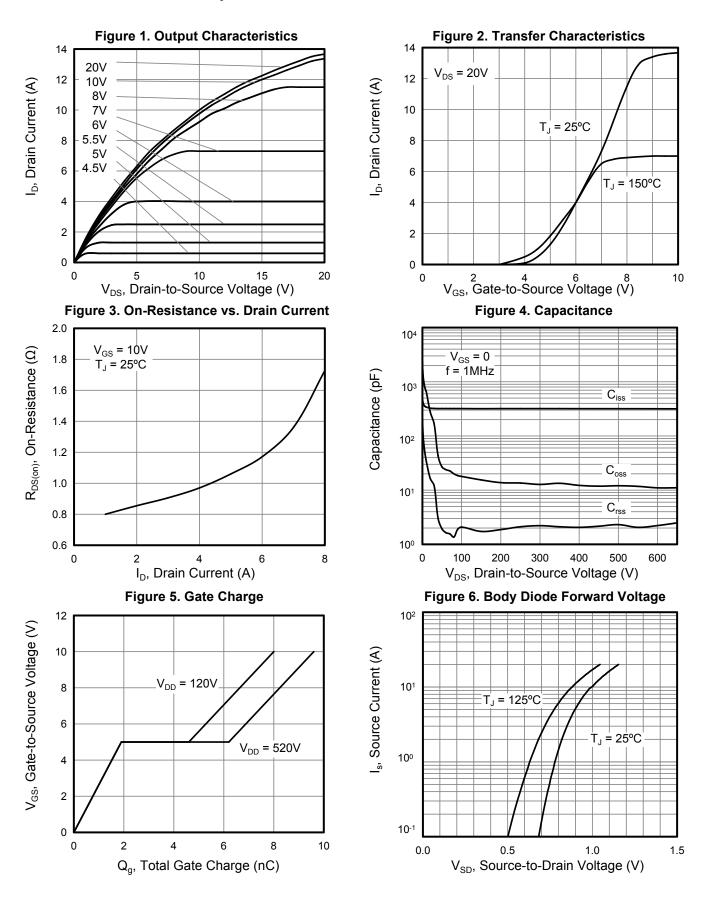


Electrical Characteristics T _J = 25°C, unless otherwise noted						
Barrantar	Ob. a.l.	Combal Took Conditions	Value			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	650			V
Zero Gate Voltage Drain Current		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$	-		1	
Zeio Gate Voltage Diam Current	I _{DSS}	V_{DS} = 650V, V_{GS} = 0V, T_{J} = 150°C	-		100	μA
Gate-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V$	-		±1	μΑ
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.0	V
Drain-Source On-State-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 2A		0.87	0.95	Ω
Gate Resistance	R_G	f = 1.0MHz open drain		5		Ω
Dynamic Characteristics				•		
Input Capacitance	C _{iss}	V _{GS} = 0V,		320		pF
Output Capacitance	C _{oss}	$V_{DS} = 100V$,		18		
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		2.1		
Total Gate Charge	Q_g		1	9.6		
Gate-Source Charge	Q_{gs}	$V_{DD} = 520V, I_{D} = 4.5A,$ $V_{GS} = 10V$		1.9		nC
Gate-Drain Charge	Q_{gd}	55		4.3		
Turn-on Delay Time	t _{d(on)}			54		
Turn-on Rise Time	t _r	$V_{DD} = 400V, I_{D} = 4.5A,$		62		20
Turn-off Delay Time	$t_{d(off)}$	$R_G = 25\Omega$		86		ns
Turn-off Fall Time	t _f			51		
Drain-Source Body Diode Characteristics						
Body Diode Forward Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 2\text{A}, V_{GS} = 0\text{V}$		0.9	1.2	V
Reverse Recovery Time	t _{rr}		-	271		ns
Reverse Recovery Charge	Q _{rr}	$V_R = 400V, I_F = 4.5A,$ $di_F/dt = 100A/\mu s$		3.1		μC
Peak Reverse Recovery Current	I _{rrm}			23		Α

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 1.0A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. Identical low side and high side switch with identical $R_{\rm G}$

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs.

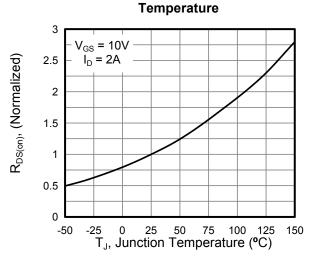


Figure 9. Transient Thermal Impedance For

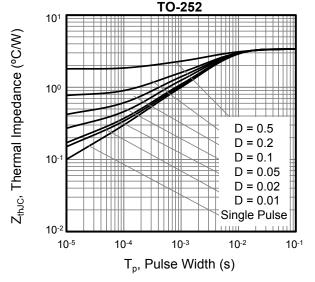


Figure 11. Safe Operation Area For TO-252

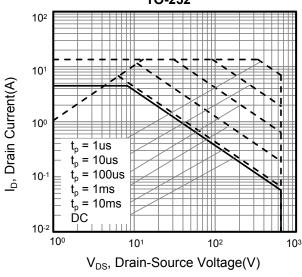


Figure 8. Breakdown voltage vs. Junction Temperature

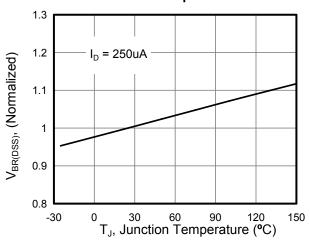


Figure 10. Transient Thermal Impedance For

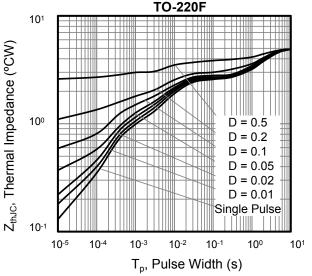
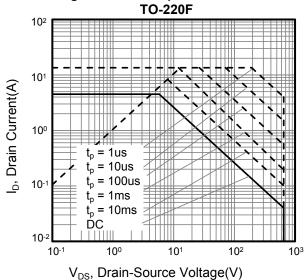


Figure 12. Safe Operation Area For





Typical Characteristics $T_J = 25$ °C, unless otherwise noted

Figure 13. Typ. Coss Stored Energy

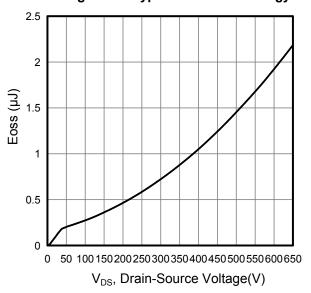




Figure A: Gate Charge Test Circuit and Waveform

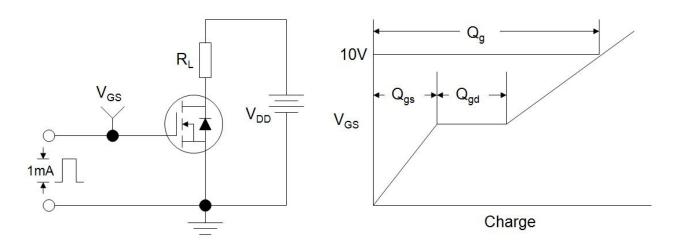


Figure B: Resistive Switching Test Circuit and Waveform

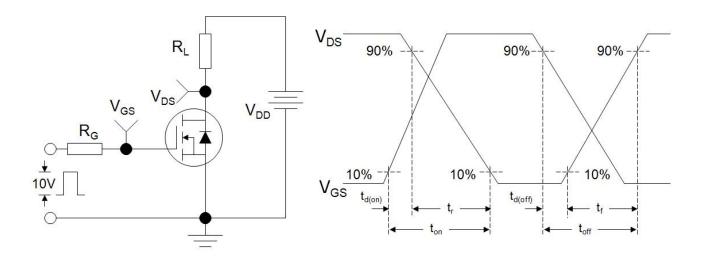
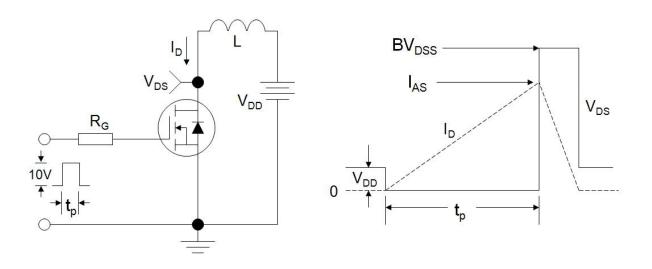


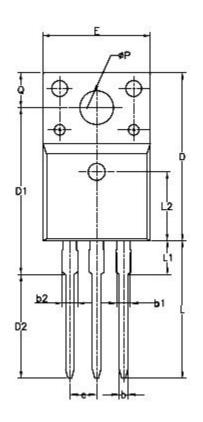
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

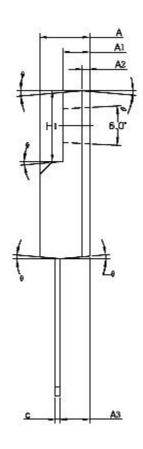


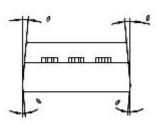
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TO-220F (集佳)



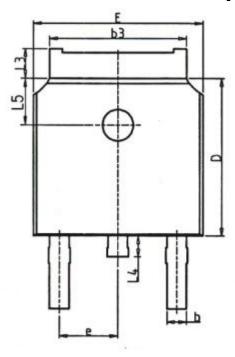


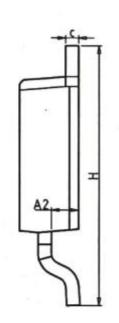


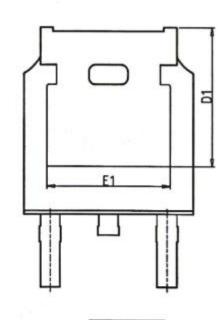
SYMBOL	MIN	NOM	MAX	
Α	4.50	4.70	4.83	
A1	2.34	2.54	2.74	
A2		0.70 R	ΞF	
A3	2.56	2.76	2.93	
b	0.70	-	0.90	
b1	1.18	1	1.38	
b2	_	-	1.47	
С	0.45	0.50	0.60	
D	15.67	15.87	16.07	
D1	15.55	15.75	15.95	
D2	9.60	9.80	10.0	
E	9.96	10.16	10.36	
е	2	2.54BSC		
H1	6.48	6.68	6.88	
L	12.68	12.98	13.28	
L1	_	-	3.50	
L2	6.50REF			
ØΡ	3.08	3.18	3.28	
Q	3.20	_	3.40	
θ1	1*	3.	5 °	

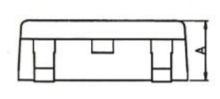


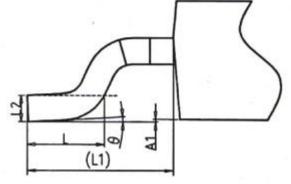
TO-252(华羿)





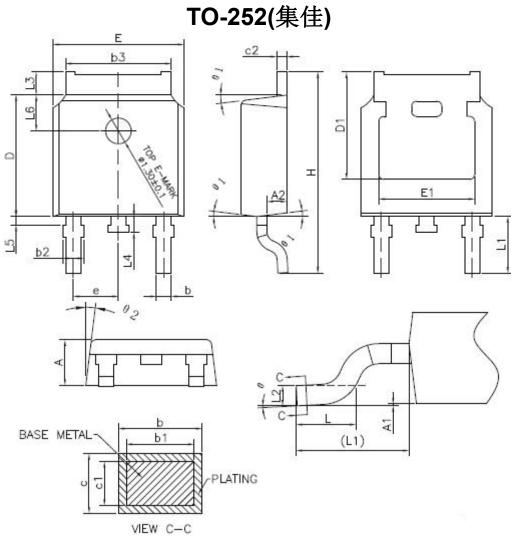






Unit:mm				
Symbol	Min.	Nom	Max.	
Α	2.20	2.30	2.38	
A1	0.00	-	0.20	
A2	0.97	1.07	1.17	
b	0.68	0.78	0.90	
b3	5.20	5.33	546	
С	0.43	0.53	0.61	
D	5.98	6.10	6.22	
D1	5.30 REF			
Е	6.40	6.60	6.73	
E1	4.63	-	-	

Unit:mm				
Symbol	Min.	Nom	Max.	
е		2.286 BSC		
Н	9.40	10.10	10.50	
L	1.38	1.50	1.75	
L1	2.90 REF			
L2		0.51 BSC		
L3	0.88	-	1.28	
L4	0.50	-	1.00	
L5	1.65	1.80	1.95	
θ	0°	-	8°	



SYMBOL	MIN	NOM	MAX
A	2,20	2,30	2,38
A1	0	-	0,10
A2	0,90	1,01	1,10
b	0.72		0.85
b1	0.71	0.76	0.81
b2	0.72	_	0.90
b3	5.13	5.33	5.46
c	0.47		0.60
c1	0,46	0,51	0,56
c2	0,47		0,60
D	6,00	6,10	6,20
D1	5,25		38-10
E	6.50	6.60	6.70
E1	4.70	-	35-33
e	2.186	2.286	2,386
Н	9.80	10.10	10.40
L	1,40	1,50	1,70
L1	2	.90 REF	
L2	0,	508 BSC	
L3	0,90		1,25
L4	0,60	0,80	1,00
L5	0.15		0.75
L6		.80 REF	
θ	0°		80
01	5°	7°	90
02	5°	70	90



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